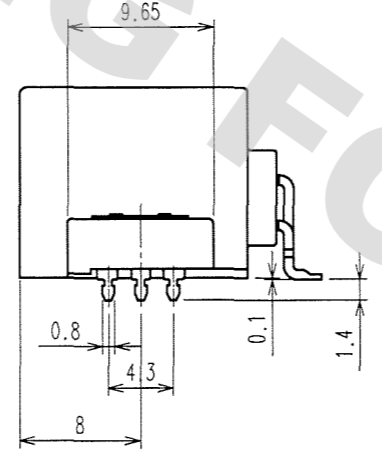
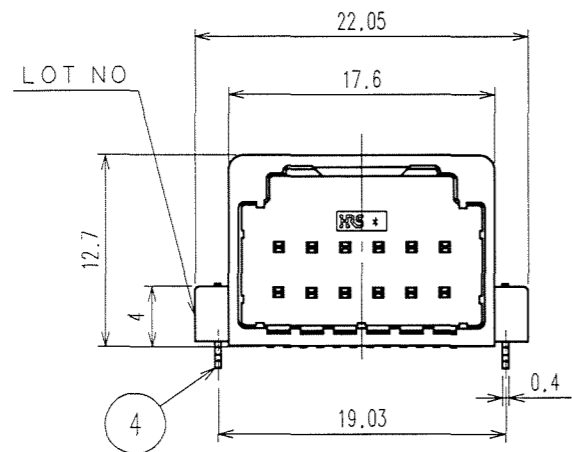
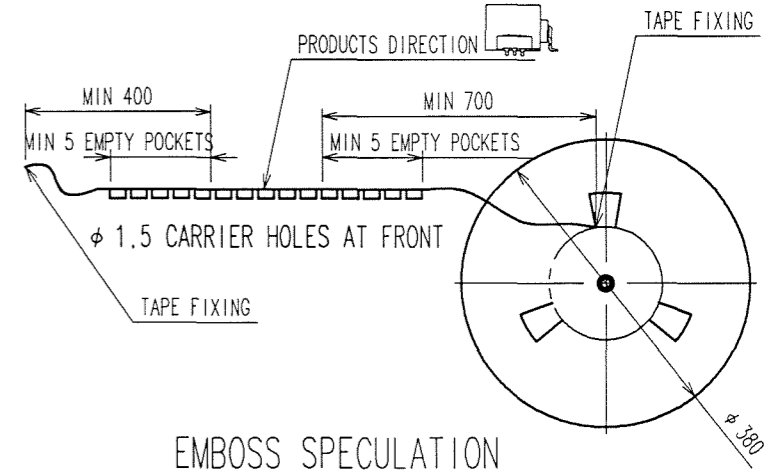
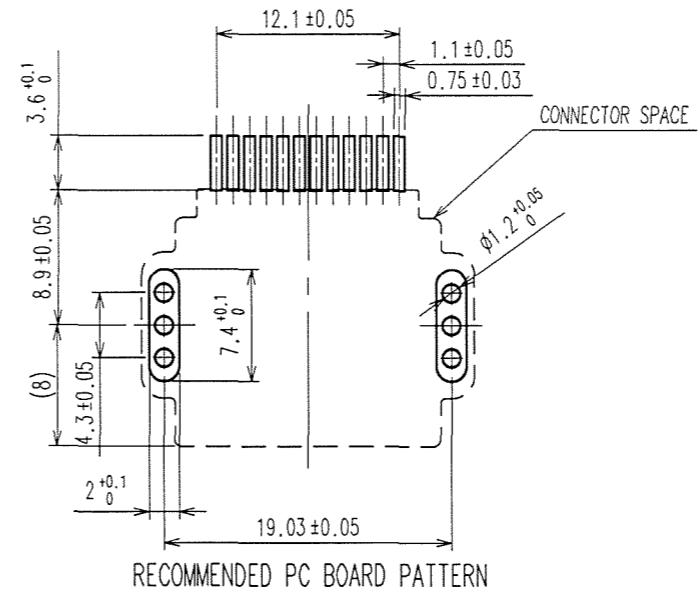
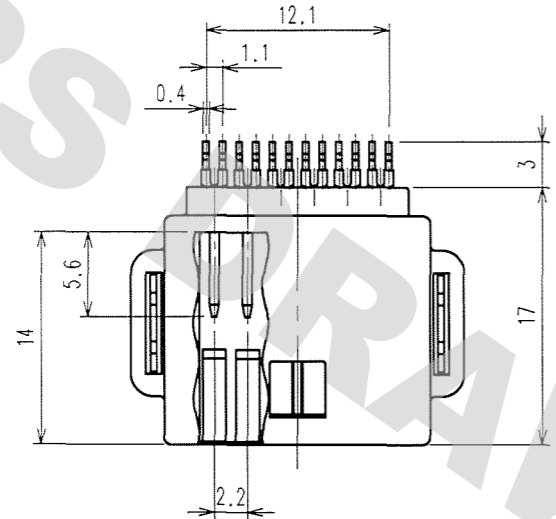


ELV, RoHS

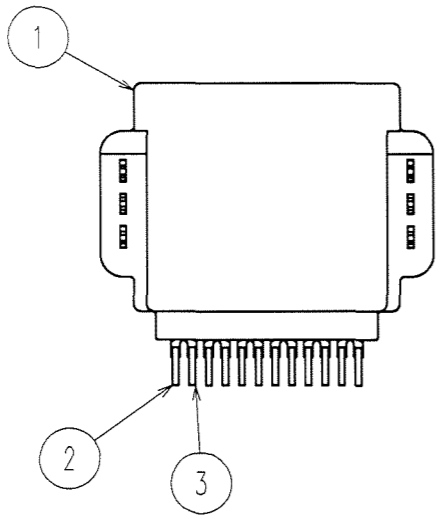
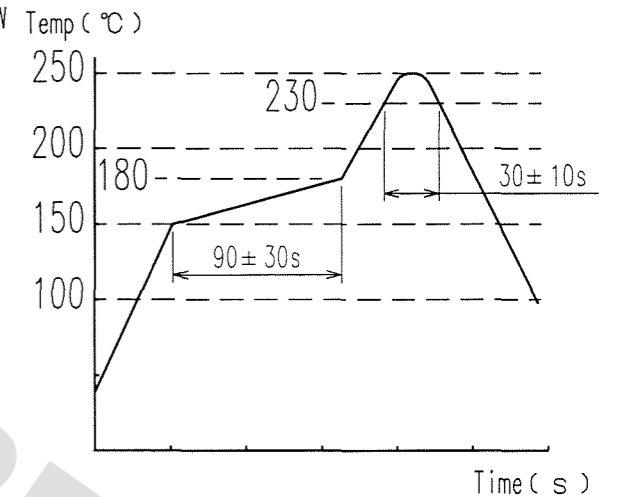
COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
△				..	△				..
△				..	△				..
△				..	△				..



NOTE 1 . RECOMMENDED TEMPERATURE PROFILE FOR REFLOW
 (REFER TO RIGHT FIG.)
 USED REFLOW SYSTEM : IR IN THE AIR OR NITROGEN
 NO. OF CYCLES : 2 MAX
 PEAK : 250°C
 OVER 230°C : 20~40s
 PREHEAT : 150~180°C
 60~120s

2 . TEMPERATURE FOR SOLDERING IRON : 280~300°C WITHIN 2s

3 . CO-PLANARITY SHALL BE 0.1 MAX.
 4 . PC BOARD THICKNESS=1.6.
 5 . RECOMMENDED SOLDER THICKNESS=0.15



2	BRASS	TIN PLATED	T=0.64	4	BRASS	TIN PLATED	T=0.4
1	PPS	LIGHT GRAY		3	BRASS	TIN PLATED	T=0.64
NO.	MATERIAL	FINISH, REMARKS		NO.	MATERIAL	FINISH, REMARKS	

UNLESS OTHERWISE SPECIFIED, SEE TABLE FOR TOLERANCES

OVER	TO	TOLERANCE
	6	±0.3
6	18	±0.5
18	50	±0.7
50	125	±1
125	250	±1.3
250	500	±2
ANGULAR		±1

CODE NO. (OLD) CL

DRAWN T.SAKASHITA '07. 3. 1

DESIGNED T.SAKASHITA '07. 3. 1

CHECKED A. Shimai '07. 3. 1

APPROVED K. Aoto '07. 3. 1

RELEASED

DRAWING NO. EDC3-166407

SCALE 2 : 1

UNITS mm

PART NO. GT25-12DP-2.2H

CODE NO. CL775-0005-4

HRS HIROSE ELECTRIC CO., LTD

DRAWING FOR REFERENCE: This is subject to change without notice 08/11/2012

TO
MYS
AMC